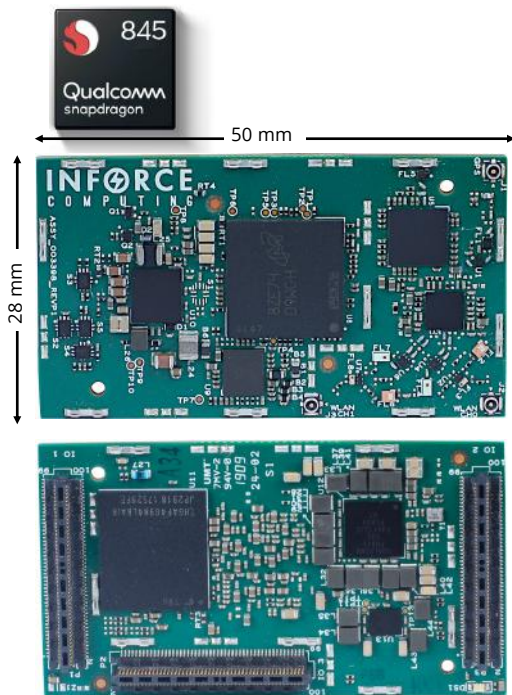




## Inforce 67X1™ Micro SoM

Qualcomm® Snapdragon™ 845 Processor based System-on-Module



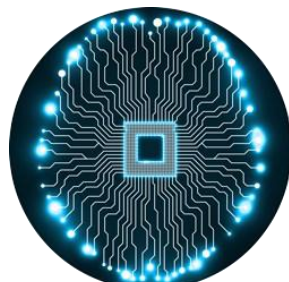
### A compact compute module featuring on-device AI and Immersion for Embedded Applications

The Inforce 67X1 SoM is a small compute module that integrates Qualcomm®Kryo™ 385 CPU, Adreno™ 630 GPU, Hexagon™ 685 DSP, Spectra™ 280 camera ISP and Qualcomm's 3<sup>rd</sup> generation AI-Engine. This enables optimized AI performance for a more responsive, power-efficient user-experience and capture of cinema-grade videos in UHD@60fps resolution.

These components, coupled with 2x2 802.11ac Wi-Fi, BT 5.x, a full featured USB-C interface with UHD display capability and high fidelity audio make the Inforce 67X1 SoM a perfect fit for applications that necessitate on-device AI and immersive multimedia experiences. Optional SKUs support extended operating temperature range and EMI shielding for better RF noise protection, while also doubling up as a medium for heat spreading and dissipation to further improve performance.



Connected Cameras



On-device AI



Wearables



Portable Healthcare



Higher performance with Qualcomm Kryo 385 CPU with independent efficiency and power clusters, each designed to optimize for a unique UX



Hexagon™ 685 DSP and Adreno™ 630 GPU featuring room-scale 6DoF with SLAM, to support on-device AI and Efficient rendering of advanced 3D graphics



Dual 14-bit Spectra™ 280 ISPs support up to 16MP for simultaneous concurrent cameras



Qualcomm Content Protection Framework; Secure Boot; Storage and Debug security



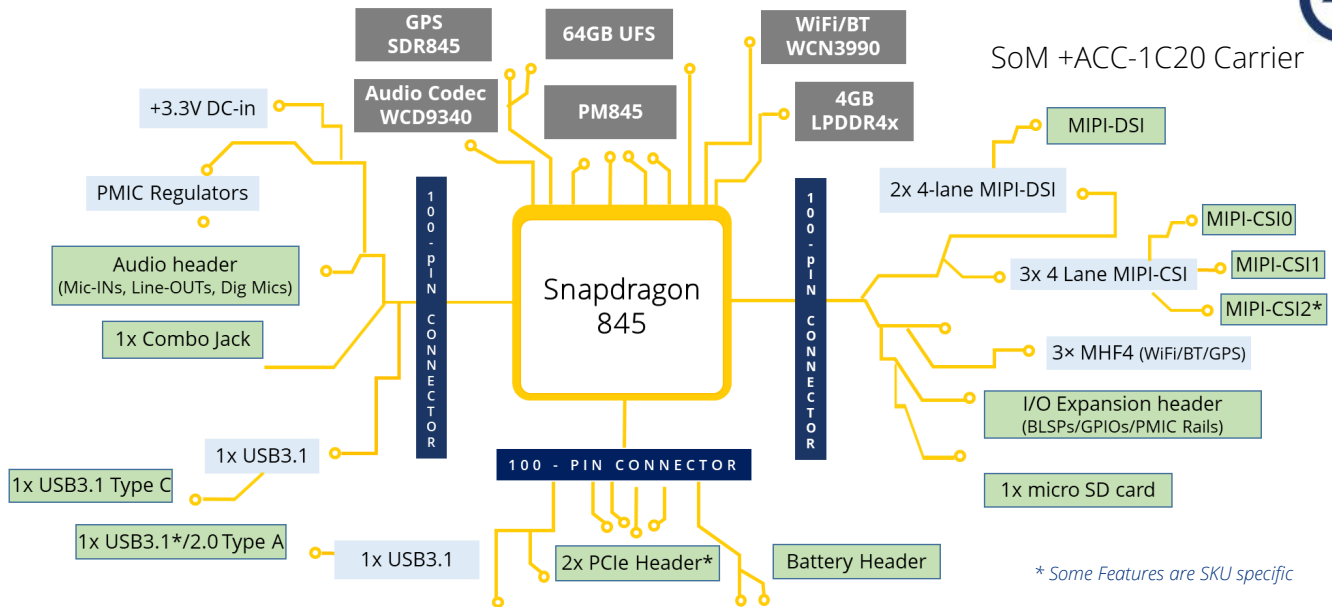
Extended lifecycle; OEM engagement options for BTO and custom variants



Production-ready with volume-conscious pricing



Dedicated Technical Support from Inforce TechWeb



\* Some Features are SKU specific

## Technical Specifications

### Processors

- ◆ Custom 64-bit Kryo Octocore ARM® V-8 compliant CPU (SDA845 SoC) @2.8/1.8GHz each
- ◆ Qualcomm® Adreno™ 630 GPU with support for OpenGL ES 3.2, Vulkan 2 and OpenCL
- ◆ Qualcomm® Hexagon™ 685 DSP with dual-HVX512 for ultra low-power audio processing

### Memory / Storage

- ◆ 4GB LPDDR4 RAM/64GB UFS
- ◆ SD V3.0 µSD card interface
- ◆ 2x USB 3.1 interfaces off which one is USB-C (USB 3.1/Gen1)

### Connectivity

- ◆ 802.11n/ac MU-MIMO WiFi and BT/LE 5.x via WCN3990
- ◆ GPS/GLONASS via SDR845
- ◆ 1x 1-lane PCIe Gen 2 and 1x 1-lane PCIe Gen 3

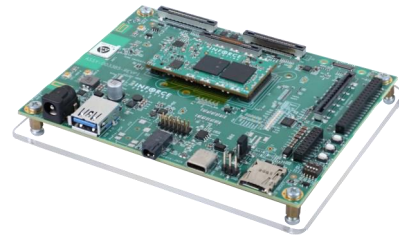
### Multimedia

- ◆ DP Alternate Mode on USB-C for 4K-DCI@24fps display
- ◆ Concurrent 4K60 10b encode + 4K60 10b decode
- ◆ Dual 4-lane MIPI-CSI lines for HEVC capture @4K60

### Software

- ◆ Android 9 BSP pre-loaded with Hexagon/SNPE/OpenCV SDKs enabled
- ◆ Debian Linux BSP

## Carrier Board For Inforce 67X1 SoM



- ◆ ACC1C20 - A small but complete carrier that brings out all native interfaces of the SDA845 processor including USB-C to help create and optimize your products with the shortest turnaround time.

### Other Specifications

- ◆ **Power:** +3.8V/6A Input
- ◆ **Operating Temp:** Commercial grade
- ◆ **Relative Humidity:** 5 to 95% non-condensing
- ◆ RoHS and WEE compliant

### Ordering Info

Part Number	Description
◆ IFC6701-00-P1	Micro SoM (Android Pie OS); 2x B2B conn; Commercial Temp support (0° - 70°C)
◆ IFC67A1-00-P1*	Micro SoM (Android Pie OS); 3x B2B conn; Commercial Temp support (0° - 70°C)
◆ SYS6701-00-P1	IFC6701-00-P1 SoM based Ref Design
◆ SYS67A1-00-P1*	IFC67A1-00-P1 SoM based Ref Design

\* - BTO SKU. MOQ of 100

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